

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

SHIOYA et al

Serial No.: 09/988,685

Filed: November 20, 2001

For: SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURING THE
SAME



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) Group Art Unit: 2813
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) Examiner: David L. Hogans
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2813
19/IDS
1.87402e
10-29-03

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97(b)(3)


Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

It is respectfully requested that the examiner consider and cite of record the references listed on the attached, copies of which are submitted herewith.

The references cited here are those brought to applicants' attention by citation in an office action from the Japanese Patent Office dated May 20, 2003 and issued in connection with Application No. 2001-345725, the priority of which is claimed here and which is believed to correspond to the captioned application. A copy of the Japanese Office Action of May 20, 2003 is enclosed herewith, along with a partial English translation thereof and a listing of the seven cited references with corresponding applications listed where known.

The examiner will note that Kokai 11-016906 and 07-230991 are both accompanied by published English language abstracts and English translation.



Japanese Kokai 10-199881 is accompanied by a copy of U.S. 6,153,507 believed to be an equivalent thereof.

Japanese Kokai 11-288931 is accompanied by a copy of published U.S. Application No. 2001/0021590 believed to correspond thereto.

Japanese Kokai 09-008033 is accompanied by both a published English language abstract thereof and an English translation thereof.

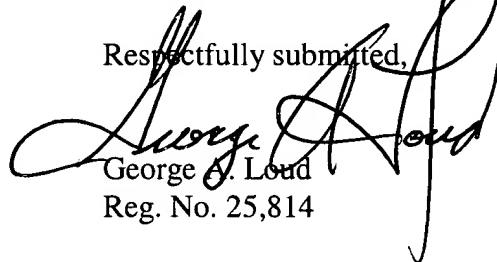
Japanese Kokai 2002-526916 is accompanied by a copy of the international publication published as WO 00/194498, believed to correspond thereto.

Japanese Kokai 9-185153 is accompanied by a copy of EP 0 771 886 believed to correspond thereto.

CERTIFICATION

The undersigned hereby certifies that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three (3) months prior to today's date.

Respectfully submitted,



George A. Loud
Reg. No. 25,814

Dated: July 30, 2003

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INFORMATION DISCLOSURE CITATION
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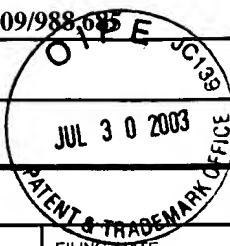
SHIOYA et al

FILING

20 NOV 2001

GROUP

JUL 30 2003



U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	6,153,507	11/28/00	MIKAGI	438	618	
	2001/0021590 A1	9/13/01	MATSUKI	438	780	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	11-16906	1/22/99	JP				
	7-230991	5/29/95	JP				
	10-199881	7/31/98	JP				
	11-288931	10/19/99	JP				
	9-8033	1/10/97	JP				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO
	00/19498	6/4/00	WO				
	2002-526916	8/20/02	JP				
	0 771 886 A1	30/10/96	EP				
	9-186153	7/15/97	JP				

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